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Anzai (43) **Pub. Date: Jan. 22, 2004**(54) **DISPLAY DEVICE**(52) **U.S. Cl. 345/76**(75) **Inventor: Katsuya Anzai, Anpachi-gun (JP)**

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City (JP)(21) **Appl. No.: 10/426,023**(22) **Filed: Apr. 30, 2003**(30) **Foreign Application Priority Data**

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Publication Classification(51) **Int. Cl.⁷ G09G 3/30**(57) **ABSTRACT**

A source of a driving transistor for driving an organic EL element functions as a first capacitance electrode layer. A second capacitance electrode layer is formed on the source through a gate insulating film of the driving transistor. The second capacitance electrode layer is formed with the same layer and by the same process as the gate electrode. A third capacitance electrode layer is formed extending over the second capacitance electrode layer through the interlayer insulating film. The third capacitance electrode layer is formed with the same layer as the drain electrode and the drain signal line. The third capacitance electrode layer is connected to the source of the driving transistor. The forming area of the storage capacitance element for holding the video signal supplied to the gate of the driving transistor can be thus reduced, improving display quality as well as extending life span of the organic EL element.

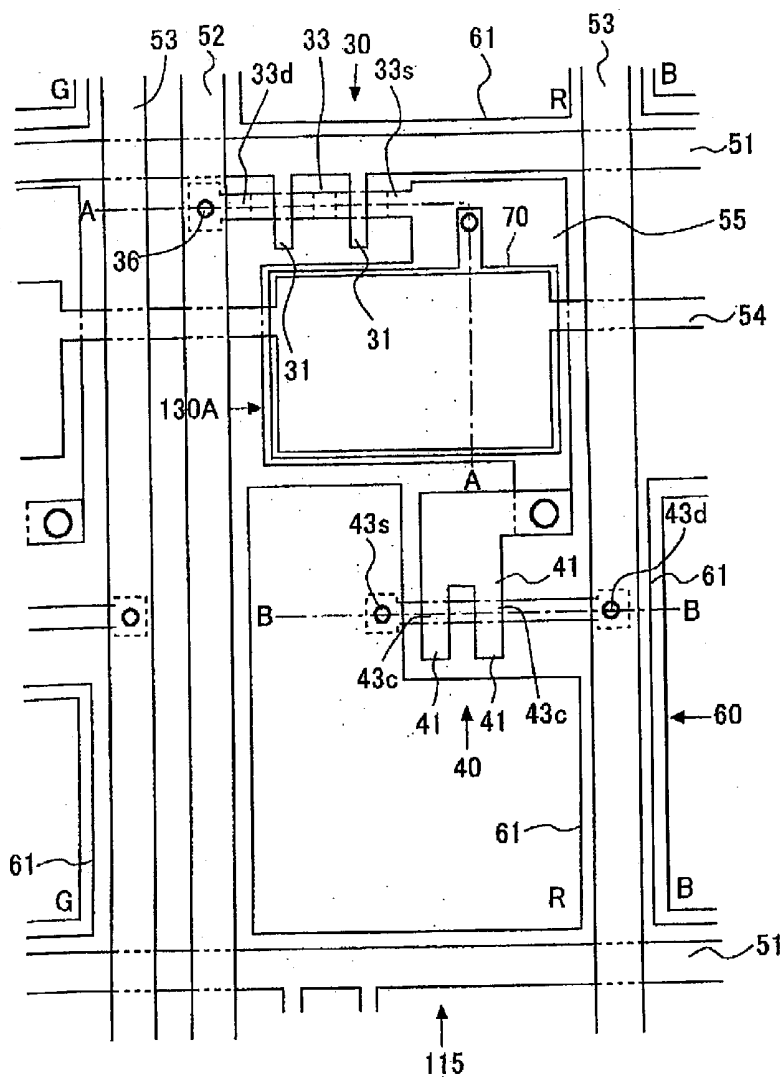


FIG. 1

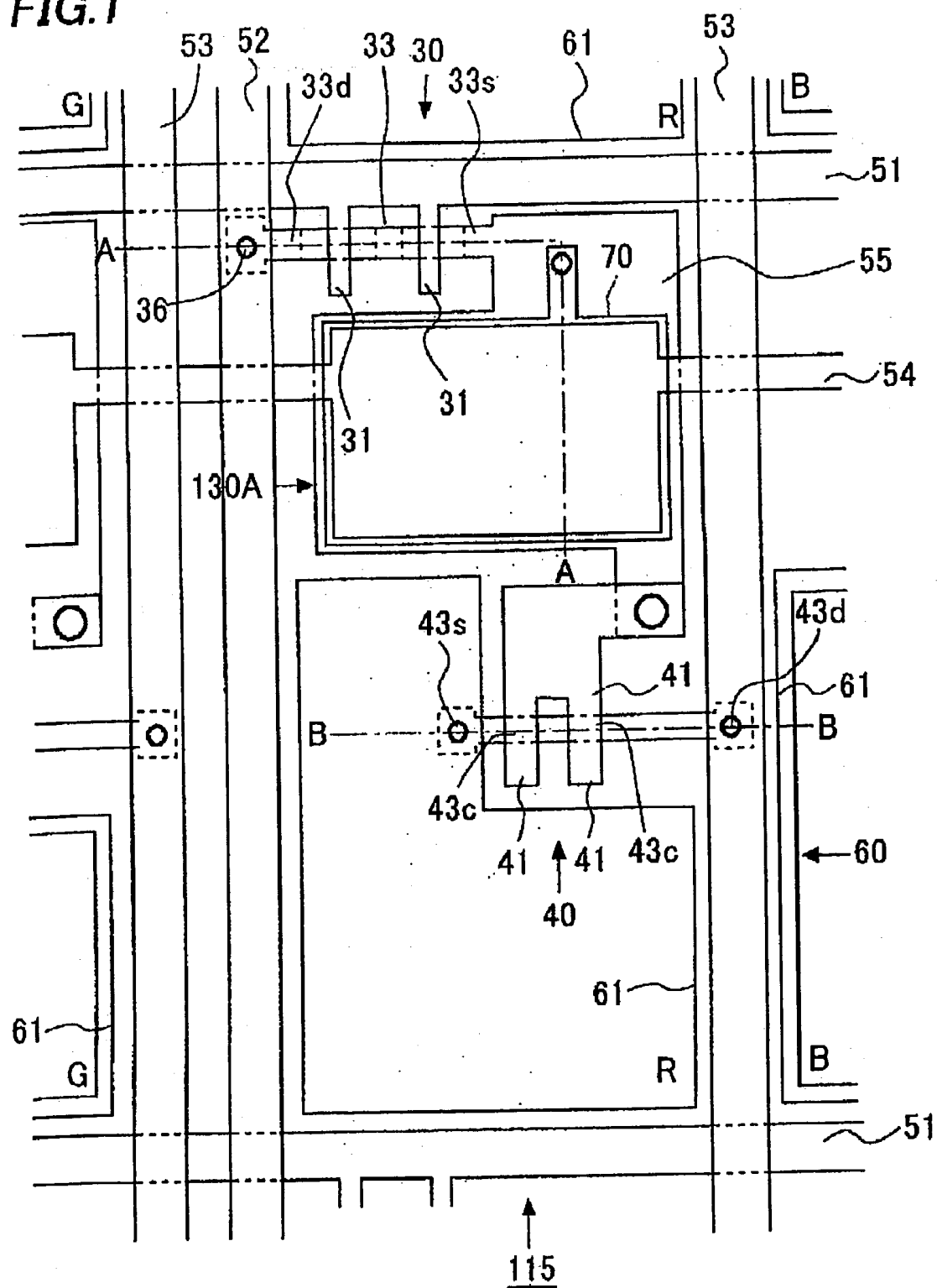


FIG.2A

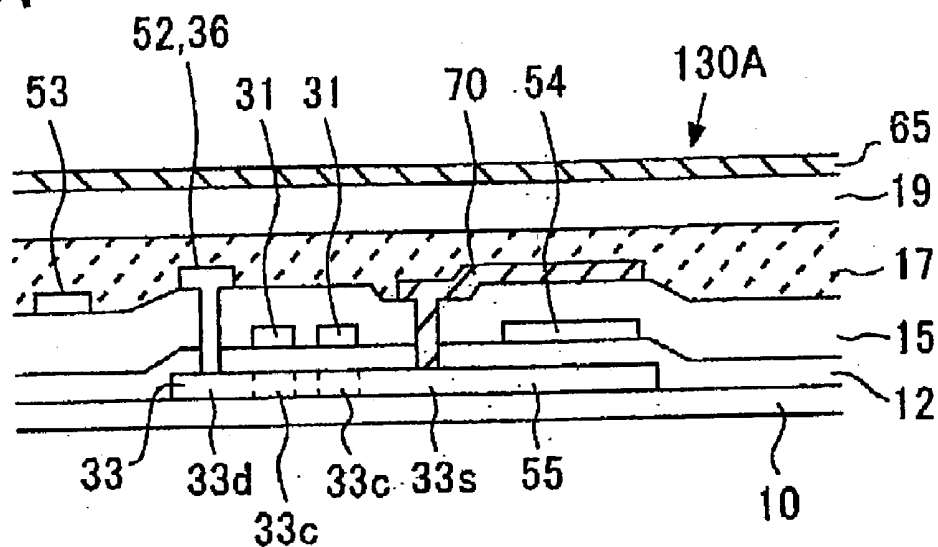


FIG.2B

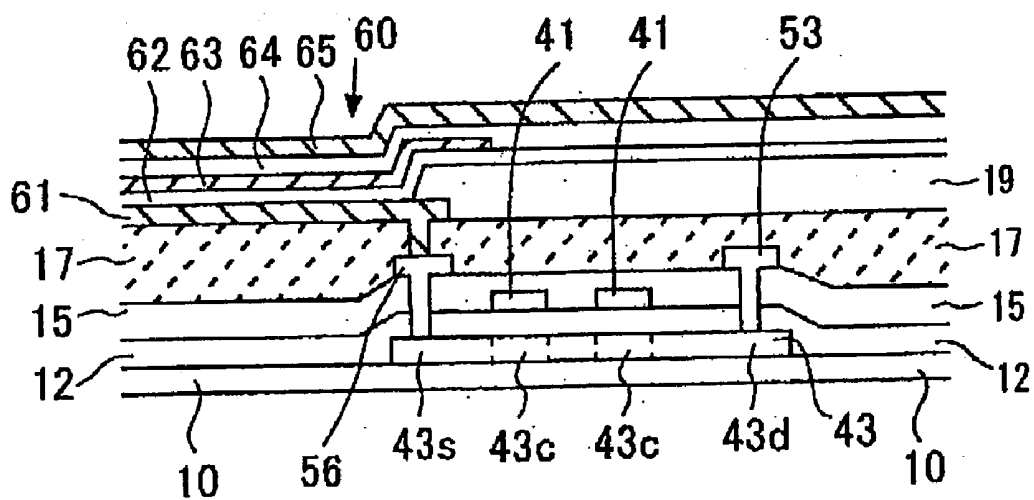


FIG.3A

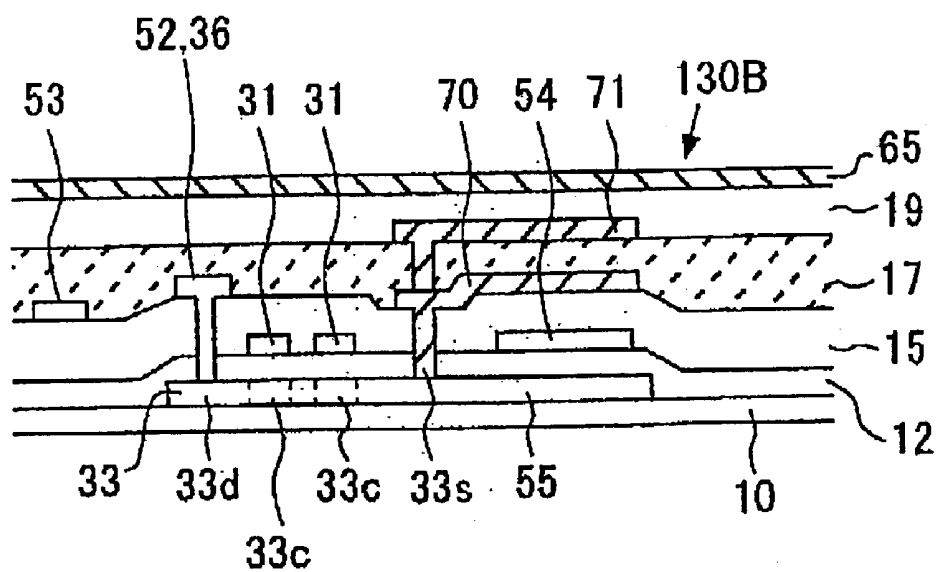


FIG.3B

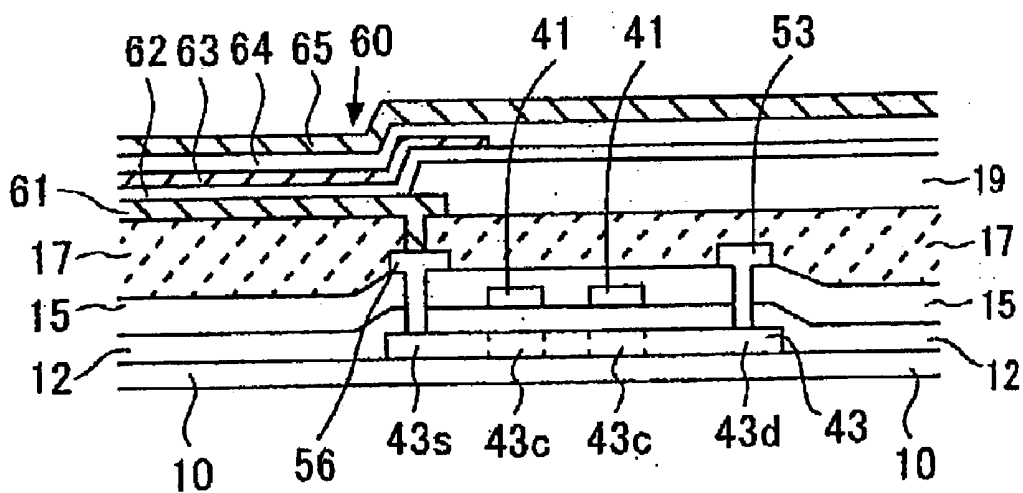


FIG. 4

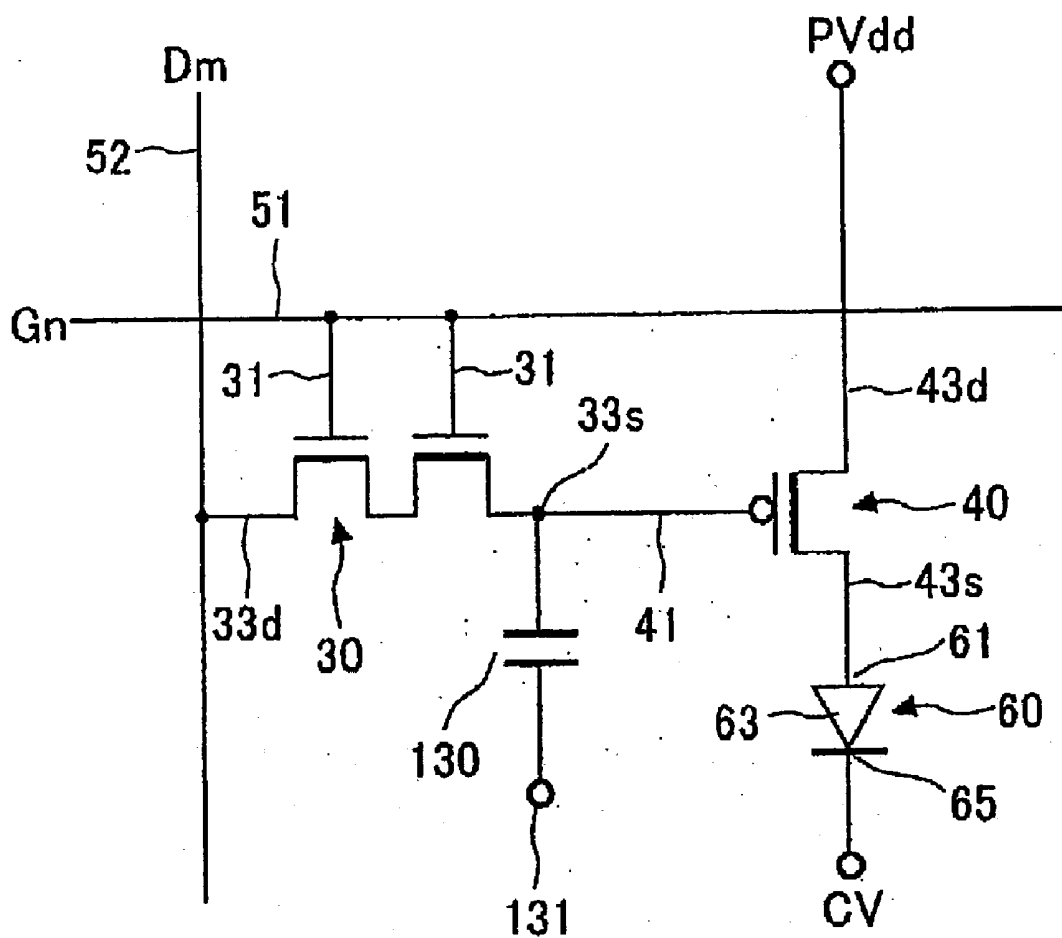
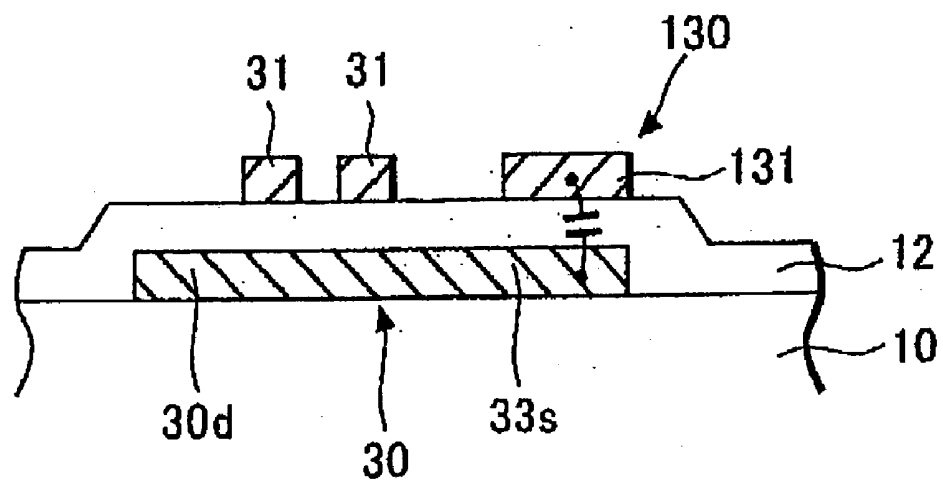


FIG. 5



DISPLAY DEVICE

BACKGROUND OF THE INVENTION

[0001] 1. Field of the Invention

[0002] This invention relates to an electroluminescent display device, especially to an electroluminescent display device with a storage capacitance element for holding a video signal supplied to a gate of a driving transistor.

[0003] 2. Description of the Related Art

[0004] An electroluminescent (referred to as EL hereinafter) display device with an EL element has been gathering attention as a display device substituting a CRT or an LCD. The development effort for the EL display device with a thin film transistor (referred to as TFT hereinafter) as a switching element for driving the EL element has been made accordingly.

[0005] FIG. 4 is an equivalent circuit diagram of one pixel of an organic EL display device. A gate signal line 51 for supplying a gate signal Gn and a drain signal line 52 for supplying a drain signal, a video signal Dm, cross each other.

[0006] An organic EL element 60, a driving TFT 40 for driving the organic EL element 60, and a pixel selecting TFT 30 for selecting the pixel are disposed near the crossing of the two signal lines. The TFT 40 is P-channel type and the TFT 30 is N-channel type.

[0007] A drain 43d of the organic EL element driving TFT 40 is provided with a plus source voltage PVdd. A source 43s of the TFT 40 is connected to an anode 61 of the organic EL element 60.

[0008] The gate signal line 51 is connected to a gate 31 of the pixel selecting TFT 30 and provided with the gate signal Gn. The drain signal line 52 is connected to a drain 33d of the pixel selecting TFT 30 and provided with the video signal Dm. A source 33s of the TFT 30 is connected to a gate 41 of the TFT 40. The gate signal Gn is outputted from a gate driver circuit not shown in the figure, and the video signal Dm is outputted from a drain driver circuit not shown in the figure.

[0009] Also, the organic EL element 60 includes the anode 61, a cathode 65, and an emissive layer 63 inserted between the anode 61 and the cathode 65. The cathode 65 is provided with a minus source voltage CV.

[0010] A storage capacitance element 130 is connected to the gate 41 of the TFT 40. That is, one of the electrodes of the storage capacitance element 130 is connected to the gate 41, and the other electrode is connected to a storage capacitance electrode 131. The storage capacitance element 130 is disposed in order to hold the video signal Dm of the display pixel for one field period by keeping the electric charge corresponding to the video signal Dm.

[0011] The operation of the EL display device with the above configuration is as follows. The TFT 30 turns on when the gate signal Gn becomes high level for one horizontal period. Then, the video signal Dm is supplied from the drain signal line 52 to the gate 41 of the TFT 40 through the TFT 30. The conductance of the TFT 40 changes according to the video signal Dm supplied to the gate 41 and the correspond-

ing driving electric current is applied to the organic EL element 60 through the TFT 40. Thus, the organic EL element 60 emits light.

[0012] FIG. 5 shows a cross-sectional view of the storage capacitance element 130 mentioned above. The TFT 30 is formed on an insulating substrate 10. The TFT 30 has the source 33s, the drain 33d, and the gate 31 formed on a gate insulating film 12. The storage capacitance electrode 131 is formed on the source 33s of the TFT 30 through the gate insulating film 12. The storage capacitance electrode 131 is provided with a predetermined stable voltage.

[0013] The storage capacitance element 130 is disposed for each of the pixels, in the conventional organic EL display device, in order to maintain the voltage applied to the gate of the driving transistor for controlling the quantity of the electric current, which determines the luminescence of the organic EL element 60.

[0014] When the voltage of the video signal Dm supplied to the pixel drops by a large quantity, it will affect the quality of the display. Therefore, a large capacitance value of the storage capacitance element 130 is required. That is, the area of the storage capacitance element 130 should be large.

[0015] There are a top emission type and a bottom emission type among the organic EL display devices. The light emitted from the organic EL element 60 radiates from the side of the organic EL element 60 opposite from the insulating substrate 10 in the top emission type display device. That is, the light radiates from the upper surface of the panel. On the other hand, the light emitted from the organic EL element 60 radiates from the side of the insulating substrate 10 in the bottom emission type display device.

[0016] When the area of the storage capacitance element 130 is large, it does not create any problem in the top emission type organic EL display device. However, the portion where the storage capacitance element is formed works as a blind in the bottom emission type display device, leading to decreased open aperture. In this configuration, the electric current supplied to the organic EL element should be increased in order to acquire the necessary luminescence, compared to the case where the device has an enough open aperture. As a result, the life span of the organic EL element is shortened.

SUMMARY OF THE INVENTION

[0017] The invention provides an electroluminescent display device having a plurality of pixel portions. Each of the pixel portions includes an electroluminescent element, a driving transistor driving the electroluminescent element, a drain signal line, and a pixel selecting transistor supplying a signal from the drain signal line to a gate of the driving transistor. The pixel portion also includes a storage capacitance element holding the signal supplied to the gate of the driving transistor. The storage capacitance element includes an extension of a source of the pixel selecting transistor as a first capacitance electrode layer, a second capacitance electrode layer disposed above the extension of the source and a third capacitance electrode layer connected to the source and disposed above the second capacitance electrode layer.

[0018] The invention also provides an electroluminescent display device having a plurality of pixel portions. Each of

the pixel portions includes an electroluminescent element having an anode layer, an emissive layer and a cathode layer, a driving transistor driving the electroluminescent element, a drain signal line, and a pixel selecting transistor supplying a signal from the drain signal line to a gate of the driving transistor. The pixel portion also includes a storage capacitance element holding the signal supplied to the gate of the driving transistor. The storage capacitance element includes an extension of a source of the pixel selecting transistor as a first capacitance electrode layer, a second capacitance electrode layer disposed above the extension of the source, a third capacitance electrode layer connected to the source and disposed above the second capacitance electrode layer, a fourth capacitance electrode layer connected to the third capacitance electrode layer and disposed above the third capacitance electrode layer and a fifth capacitance electrode layer disposed above the fourth capacitance electrode layer.

BRIEF DESCRIPTION OF THE DRAWINGS

[0019] **FIG. 1** is a plan view of one pixel portion of an organic EL display device of a first embodiment of this invention.

[0020] **FIGS. 2A and 2B** are cross-sectional views of the pixel portion of **FIG. 1**.

[0021] **FIGS. 3A and 3B** are cross-sectional views of a pixel portion of an organic EL display device of a second embodiment of this invention.

[0022] **FIG. 4** is an equivalent circuit diagram of a pixel portion of a conventional organic EL display device.

[0023] **FIG. 5** is a cross-sectional view of the pixel portion of **FIG. 4**.

DETAILED DESCRIPTION OF THE INVENTION

[0024] A first embodiment of this invention will be explained hereinafter. **FIG. 1** is a plan view showing a pixel portion of an organic EL display device. **FIG. 2A** is a cross-sectional view of one pixel portion along the A-A line and, **FIG. 2B** is a cross-sectional view of the pixel portion along the B-B line in **FIG. 1**. The equivalent circuit diagram of the pixel portion is the same as shown in **FIG. 4**.

[0025] The pixel portion **115** is formed in the region surrounded with a gate signal line **51** and a drain signal line **52**, as shown in **FIGS. 1, 2A and 2B**. A plurality of pixel portions is disposed in a matrix configuration, forming a display region.

[0026] An organic EL element **60**, which is a self emissive element, a pixel election TFT **30** for controlling the timing of supplying electric current to the organic EL element **60**, an organic EL element driving TFT **40** for supplying electric current to the organic EL element **60**, and a storage capacitance element **130A** are disposed in the pixel portion **115**. The organic EL element **60** includes an anode layer **61**, an emissive layer made of an emissive material and a cathode layer **65**.

[0027] The pixel selecting TFT **30** is disposed near the crossing of a gate signal line **51** a drain signal line **52**. A source **33s** of the TFT **30** works also as a first capacitance electrode layer **55**, and is connected to a gate **41** of the TFT **40**. A second capacitance electrode layer **54** is formed above

the source **33s** of the TFT **30** through a gate insulating film **12**. The second capacitance electrode layer **54** is made of chrome or molybdenum, and disposed parallel to the gate signal line **51**. Also, a third capacitance electrode layer **70** is formed above the second capacitance electrode layer **54** through an interlayer insulating film **15**.

[0028] A source **43s** of the organic EL element driving TFT **40** is connected to the anode layer **61** of the organic EL element **60**, and a drain **43d** is connected to a driving source line **53**, which is an electric source supplied to the organic EL element **60**.

[0029] The organic EL display device includes the TFTs and the organic EL element deposited sequentially on an insulating substrate **10**, which is either a substrate made of a glass, a synthetic resin, a conductive material or a semiconductor, as shown in **FIGS. 2A and 2B**. When a conductive substrate or a semiconductor substrate is used as the insulating substrate **10**, an insulating film **12** such as a SiO₂ film or a SiN film should first be disposed before forming the TFTs **30, 40** and the organic EL element. Both TFTs have a top-gate configuration, where a gate electrode is disposed above an active layer through the gate insulating film **12**.

[0030] Next, the detailed configuration of the pixel selecting TFT **30** and the storage capacitance element **130A** will be explained. An amorphous silicon film (referred to as a-Si film hereinafter) is formed through a CVD method on the insulating substrate. The a-Si film is irradiated by a laser beam for re-crystallization from melt, forming a polycrystalline silicon film (referred to as a p-Si film, hereinafter). This layer functions as the active layer **33**. Single layer or multiple layers of a SiO₂ film and a SiN film are formed on the p-Si film as the gate insulating film **12**.

[0031] Then, the gate signal line **51** also working as the gate electrode **31** made of a metal with a high-melting point such as Cr and Mo as well as the drain signal line **52** made of Al are disposed. Also, the driving source line **53**, which is made of Al and is an electric source of the organic EL element **60**, is disposed.

[0032] A SiO₂ film, a SiN film and a SiO₂ film are sequentially deposited to form the interlayer insulating film **15** on the entire surface of the gate insulating film **12** and the active layer **33**. A drain electrode **36**, which is formed by filling a contact hole formed at the location corresponding to the drain **33d** with a metal such as Al, is disposed, and a first planarization film **17** made of an organic resin for flattening the surface is formed on the entire surface.

[0033] Next, the configuration of the storage capacitance element **130A** will be explained. The source **33s** of the TFT **30** functions also as the first capacitance electrode layer **55**. The second capacitance electrode layer **54** is formed above the source **33s** of the TFT **30**, through the gate insulating film **12**. The second capacitance electrode layer **54** is made of Cr or Mo, and formed in the same layer as the gate electrode **31** and by the same process as the gate electrode **31**. The third capacitance electrode layer **70** extends over the second capacitance layer **54** through the interlayer insulating film **15**. The third capacitance layer **70** is formed in the same layer as, and by the same process as the drain electrode **36** and the drain signal line **52**. The third capacitance electrode layer **70** is connected to the source **33s** of the TFT **30** through a contact hole.

[0034] That is, the storage capacitance element **130** has a multiple-layer configuration with the second capacitance electrode layer **54** sandwiched by the first capacitance electrode layer **55** and the third capacitance electrode layer **70** through the insulating films. Therefore, the storage capacitance element **130** can form a large capacitance in a relatively small area.

[0035] It is also possible to acquire the larger capacitance by extending the cathode layer **65** over the third capacitance electrode layer **70** through the first planarization film **17** and a second planarization film **19**.

[0036] Next, the organic EL element driving TFT **40** will be explained. The a-Si film is formed on the insulating substrate **10**. The a-Si film is irradiated by a laser beam for forming a poly-crystalline silicon film functioning as an active layer **43**. The gate insulating film **12**, and the gate electrode **41** made of a metal with a high-melting point such as Cr and Mo are deposited on the active layer **43**. Channels **43c** are formed in the active layer **43**. The source **43s** and the drain **43d** are also formed at both sides of the channels **43c**. A SiO₂ film, a SiN film and a SiO₂ film are sequentially deposited to form the interlayer insulating film **15** on the entire surface of the gate insulating film **12** and the active layer **43**. The driving source line **53**, which is connected to the driving source by filling a contact hole formed at the location corresponding to the drain **43d** with a metal such as Al, is disposed. A source electrode **56** is also formed by filling a contact hole formed at the location corresponding to the source **43s** with a metal such as Al.

[0037] Furthermore, the first planarization film **17** made of an organic resin for flattening the surface is deposited on the entire surface. A contact hole is formed in the first planarization film **17** at the location corresponding to the source electrode **56**. The anode layer **61** of the organic EL element, which is a transparent electrode made of ITO, making contact with the source electrode **56** through the contact hole described above is formed on the first planarization film **17**. The second planarization film **19** is further disposed on the first planarization film **17**. This film is removed from the area above the anode layer **61**.

[0038] The organic EL element **60** includes the anode layer **61** made of the transparent electrode such as ITO (Indium Tin Oxide), a hole transportation layer **62** having a first hole transportation layer made of MTDATA (4,4-bis(3-methylphenylphenylamino) biphenyl) and a second hole transportation layer made of TPD (4,4,4-tris (3-methylphenylphenylamino) triphenylamine), an emissive layer **63** made of Bebq2 (bis(10-hydroxybenzo[h]quinolinato)beryllium) including quinacridone derivative, an electron transportation layer **64** made of Bebq2, and the cathode layer **65** made of either magnesium-indium alloy, aluminum or aluminum alloy.

[0039] The holes inputted from the anode layer **61** and the electrons inputted from the cathode layer **65** are re-combined in the emissive layer of the organic EL element **60**, activating organic molecules in the emissive layer. When the activated molecules are deactivated due to radiation, light is emitted from the emissive layer, and light then reaches outside through the transparent anode layer **61** and the insulating substrate **10**.

[0040] Next, a second embodiment of this invention will be explained. FIGS. 3A and 3B are cross-sectional views of

one pixel portion of this embodiment. FIG. 3A is a cross sectional view of the pixel portion along the A-A line of FIG. 1, and FIG. 3B is a cross sectional view along the B-B line of FIG. 1, respectively. The structure of the pixel portion of this embodiment is the same as that of the first embodiment except the capacitance electrode structure described below. The equivalent circuit diagram of the pixel portion of this embodiment is also the same as shown in FIG. 4.

[0041] The storage capacitance element **130A** has a multiple-layer configuration with the second capacitance electrode layer **54** sandwiched by the first capacitance electrode layer **55** and the third capacitance electrode layer **70** through the insulating films in the first embodiment. The storage capacitance element **130B** of the second embodiment has an additional electrode layer to increase capacitance per unit area.

[0042] A fourth capacitance electrode layer **71** is deposited extending over the third capacitance electrode layer **70** through the first planarization layer **17** in addition to the configuration of the first embodiment. The fourth capacitance electrode layer **71** is in the same layer as and formed by the same process as the anode layer **61**.

[0043] Additionally, the cathode layer **65** is deposited extending over the fourth capacitance electrode layer **71** through the second planarization layer **19**. The cathode layer **65** functions as a fifth capacitance electrode layer.

[0044] In the first embodiment, a capacitance is formed between the third capacitance electrode layer **70** and the cathode layer **65** when the cathode electrode is used as a fourth capacitance electrode layer. Both the first planarization film **17** and the second planarization film **19** function as the capacitance insulating film in this configuration. In the second embodiment, however, a capacitance is formed between the fourth capacitance electrode layer **71** and the cathode layer **65**, i.e., the fifth capacitance electrode. Since the second planarization layer **19** is the only layer working as the capacitance insulating layer in this configuration, the capacitance insulating film between the capacitance electrodes facing each other is thinner compared to that of the first embodiment. Accordingly, the corresponding capacitance increases.

What is claimed is:

1. An electroluminescent display device having a plurality of pixel portions, each of the pixel portions comprising:

- an electroluminescent element;
- a driving transistor driving the electroluminescent element;
- a drain signal line;
- a pixel selecting transistor supplying a signal from the drain signal line to a gate of the driving transistor; and
- a storage capacitance element holding the signal supplied to the gate of the driving transistor, the storage capacitance element including an extension of a source of the pixel selecting transistor as a first capacitance electrode layer, a second capacitance electrode layer disposed above the extension of the source and a third capacitance electrode layer connected to the source and disposed above the second capacitance electrode layer.

2. The electroluminescent display device of claim 1, wherein the second capacitance electrode layer is in a same wiring layer as a gate of the pixel selecting transistor.

3. The electroluminescent display device of claim 1, further comprising a gate insulating film of the pixel selecting transistor, wherein a part of the gate insulating film is disposed between the first and second capacitance electrode layers.

4. The electroluminescent display device of claim 1, wherein the third capacitance electrode layer is in a same wiring layer as the drain signal line.

5. The electroluminescent display device of claim 1, further comprising an interlayer insulating film disposed between the gate of the pixel selecting transistor and the drain signal line, wherein a part of the interlayer insulating film is disposed between the second and third capacitance electrode layers.

6. The electroluminescent display device of claim 1, further comprising a cathode electrode layer of the electroluminescent element, the cathode electrode layer extending over the third capacitance electrode layer and being configured to work as a fourth capacitance electrode layer of the storage capacitance element.

7. An electroluminescent display device having a plurality of pixel portions, each of the pixel portions comprising:

an electroluminescent element including an anode layer, an emissive layer and a cathode layer;

a driving transistor driving the electroluminescent element;

a drain signal line;

a pixel selecting transistor supplying a signal from the drain signal line to a gate of the driving transistor; and

a storage capacitance element holding the signal supplied to the gate of the driving transistor, the storage capacitance element including an extension of a source of the pixel selecting transistor as a first capacitance electrode layer, a second capacitance electrode layer disposed above the extension of the source, a third capacitance electrode layer connected to the source and disposed

above the second capacitance electrode layer, a fourth capacitance electrode layer connected to the third capacitance electrode layer and disposed above the third capacitance electrode layer and a fifth capacitance electrode layer disposed above the fourth capacitance electrode layer.

8. The electroluminescent display device of claim 7, wherein the second capacitance electrode layer is in a same wiring layer as a gate of the pixel selecting transistor.

9. The electroluminescent display device of claim 7, further comprising a gate insulating film of the pixel selecting transistor, wherein a part of the gate insulating film is disposed between the first and second capacitance electrode layers.

10. The electroluminescent display device of claim 7, wherein the third capacitance electrode layer is in a same wiring layer as the drain signal line.

11. The electroluminescent display device of claim 7, further comprising an interlayer insulating film disposed between the gate of the pixel selecting transistor and the drain signal line, wherein a part of the interlayer insulating film is disposed between the second and third capacitance electrode layers.

12. The electroluminescent display device of claim 7, wherein the fourth capacitance electrode layer is in a same wiring layer as the anode layer.

13. The electroluminescent display device of claim 7, further comprising a planarization layer disposed on the drain signal line, wherein a part of the planarization layer is disposed between the third and fourth capacitance electrode layers.

14. The electroluminescent display device of claim 7, wherein the fifth capacitance electrode layer is an extension of the cathode layer.

15. The electroluminescent display device of claim 7, further comprising a planarization layer disposed partially on the anode layer, wherein a part of the planarization layer is disposed between the fourth and fifth capacitance electrode layers.

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